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1.	03/11/1993			(includ	ing author, title, Do	te. Pertinent	Pages, Etc.)	
Ref.	Title	•						
2.	Ruvimov, S 73(18):2582	. et al. (1998). "Micro -2584.	ostructure of Ti/Al Ohmic	c Contacts	for n-A1GaN,	" Appl. P	hys. Lett.	
	Ref. No. Ref. No. 1.	Ref. Date No.  Ref. Date No. 1. 05/11/1993  Ref. Title No. 2. Ruvimov, S	U.S. PAT	(Use several sheets if necessary)  U.S. PATENT DOCUMENTS  Ref. Date Document No. Name  FOREIGN PATENT DOCUMENT  Ref. Date Document No. Country  No. 1. 05/11/1993 JP 5-291621 Japan  OTHER DOCUMENTS  Ref. No. OTHER DOCUMENTS  Ref. Title No. Revimov, S. et al. (1998). "Microstructure of Ti/Al Ohmic	(Use several sheets if necessary)  Filing Date Concurrently Herewith  Mailing Date February 3, 2004  U.S. PATENT DOCUMENTS  Ref. Date Document No. Name Class  No. FOREIGN PATENT DOCUMENTS  Ref. Date Document No. Country Class  1. 05/11/1993 JP 5-291621 Japan  OTHER DOCUMENTS (includ.  Ref. Title  No. 2. Ruvimov, S. et al. (1998). "Microstructure of Ti/Al Ohmic Contacts	IN AN APPLICATION (Use several sheets if necessary)  Filing Date Concurrently Herewith Mailing Date February 3, 2004  U.S. PATENT DOCUMENTS  Ref. Date Document No. Name Class Subclass No.  FOREIGN PATENT DOCUMENTS  Ref. Date Document No. Country Class Subclass  1. 05/11/1993 JP 5-291621 Japan  OTHER DOCUMENTS  Ref. Title No.  Ref. Title No.	Filing Date Concurrently Herewith   Group Art Unit Not Yet Assign	